Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	((neutral center) near point and corner adj point and rotat$4 and organic adj substrate).clm.	US-PGPUB	OR	ON	2005/11/22 14:56

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S9	40581	(flipchip flip adj chip flip$1chip bga)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:57
S10	108182	substrate and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:57
S11	9976	underfill$3 under?fill$3 under adj fill$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:58
S12	22154	warpage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:58
S13	21552	S9 and S10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 19:59
S14	3868	S13 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 19:59
S15	256	S14 and S12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 20:00
S16	571061	pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:00
S17	35671	solder adj (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:00
S18	34841	S16 and (cu copper) and (au gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:00

S19	7599	S16 with (cu copper) and (au gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 20:03
S20	3518	S16 with (cu copper) with (au gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:01
S21	440892	diffus$4 and (met$3 reflow$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:01

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S58	6446	(257/678,737,778).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 18:56
S59	4399	(438/457,106,108).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 18:57
S60	43015	(flipchip flip adj chip flip$1chip bga)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:57
S61	113529	substrate and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:57
S62	10640	underfill$3 under?fill$3 under adj fill$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:58
S63	22810	warpage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:58
S64	22951	S60 and S61	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:59
S65	4192	S64 and S62	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 18:59
S66	281	S65 and S63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:00
S67	591993	pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:00

S68	37493	solder adj (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:00
S69	37183	S67 and (cu copper) and (au gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:00
S70	3695	S67 with (cu copper) with (au gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:01
S71	458111	diffus$4 and (met$3 reflow$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/21 19:02
S72	43044	(flipchip flip adj chip flip$1chip bga)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 14:48
S73	113591	substrate and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 08:25
S74	592273	pad	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 08:25
S75	37515	solder adj (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 08:25
S76	3697	S74 with (cu copper) with (au gold)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 08:25
S77	458313	diffus$4 and (met$3 reflow$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 08:25

S78	293	S72 and S73 and S75 and S74 and S76 and S77	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 08:27
S79	54	S78 and organic near3 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 08:28
S80	6	("6303998").URPN.	USPAT	OR	OFF	2005/11/22 08:42
S81	1	"6747331".pn.	USPAT	OR	OFF	2005/11/22 08:42
S82	0	("6747331").URPN.	USPAT	OR	OFF	2005/11/22 08:43
S83	5	("3611317" | "4868634" | "6188582" | "6303998" | "6566234").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/22 08:43
S84	3	((neutral center) near point and corner adj point and rotat$4 and organic adj substrate).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 14:56
S85	43044	(flipchip flip adj chip flip$1chip bga)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 14:48
S86	2194	organic near substrate and (bump ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 14:49
S87	1028	S85 and S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 14:49
S88	22813	warpage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 14:49
S89	103	S87 and S88	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 14:50
S90	18	S89 and rotat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/22 14:50

S91	0	("2003/0170450").URPN.	USPAT	OR	OFF	2005/11/22 14:51
S92	0	("6906425").URPN.	USPAT	OR	OFF	2005/11/22 14:52
S93	13	("4873397" | "5061549" | "5372883" | "5401536" | "5783867" | "5930889" | "6037657" | "6084781" | "6177728" | "6238223" | "6265776" | "6297560" | "6774480").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/11/22 14:52